2SC4562

Silicon NPN epitaxial planar type

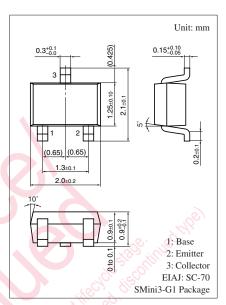
For high-frequency amplification Complementary to 2SA1748

Features

- High transition frequency f_T
- \bullet Small collector output capacitance (Common base, input open circuited) C_{ob}
- S-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

Parameter	meter Symbol Rating		Unit			
Collector-base voltage (Emitter open)	V _{CBO}	50	V			
Collector-emitter voltage (Base open)	V _{CEO}	50	V			
Emitter-base voltage (Collector open)	V _{EBO}	5	v			
Collector current	I _C	50	mA			
Collector power dissipation	P _C	150	mW			
Junction temperature	Тј	150	°C			
Storage temperature	T _{stg}	-55 to +150	°C			





Marking Symbol: AM

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

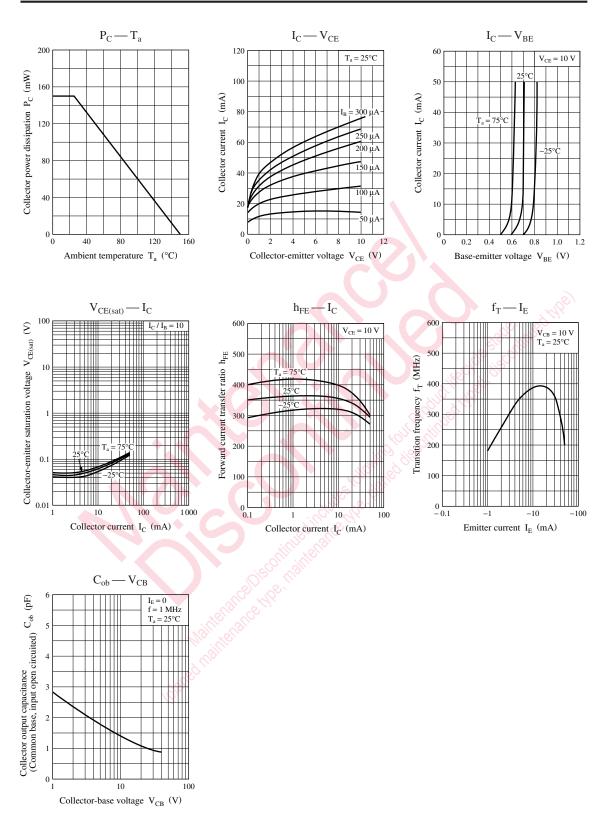
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu \text{A}, \ I_{\rm E} = 0$	50			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 1 {\rm mA}, I_{\rm B} = 0$	50			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$	5			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$			0.1	μΑ
Collector-emitter cutoff current (Base open)	I _{CEO}	$V_{CE} = 10 \text{ V}, I_B = 0$			100	μΑ
Forward current transfer ratio *	h _{FE}	$V_{CE} = 10 \text{ V}, I_C = 2 \text{ mA}$	200		500	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{C} = 10 \text{ mA}, I_{B} = 1 \text{ mA}$		0.06	0.30	V
Transition frequency	f _T	$V_{CB} = 10 \text{ V}, I_E = -2 \text{ mA}, f = 200 \text{ MHz}$		250		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		1.5		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2. *: Rank classification

Rank	Q	R
h _{FE}	200 to 400	250 to 500

Panasonic



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